DTIP 2016

Design, Test, Integration & Packaging of MEMS/MOEMS

Final Call for Papers

General Chair: Pascal NOUET, LIRMM, France
Local Chair: Marta RENCZ, BME, Hungary
Publication Chair: Benoit CHARLOT, IES, France

Budapest, Hungary
May 30th-June, 2nd-2016

Submission Deadline: November, 22th, 2015
Notification of Acceptance: January, 20th, 2016

http://www.dtip-mems.org/

Established in 1999 by our colleague Dr Bernard Courtois, DTIP is definitively the premier MEMS scientific conference in Europe.

In-line with the previous editions, DTIP'2016 will be a scientific event with two main conferences, along with special sessions and invited talks. Selected papers will appear in IEEE Xplore and their possible extended version will be submitted for publication in a special issue of an indexed journal.

Computer-Aided Design, Design and Test

Chair: Peter Schneider, Fraunhofer IIS/EAS, Dresden, Germany
Co-Chair: Francis Pressecq, CNES, France

This Conference will bring together researchers, engineers and practitioners involved in the development of CAD tools and design methodologies for MEMS and MOEMS.

Topics of Interest

CAD: Integrated CAD/CAE tools, languages and interchange of data, MEMS/MOEMS libraries and IP, Modelling and simulation of fabrication processes, Structured design methodologies, System-level design methodologies

DESIGN: Mechanical simulation, Model order reduction, Multi-physics & Multi-domain simulations, Numerical simulation, other design issues, Signal processing & Front-ends, Thermal evaluation

TEST: Failure mechanisms, Fault modelling, Fault simulation and test pattern generation, Yield estimation

DEVICES & COMPONENTS: RF MEMS, MOEMS, energy harvesting, bio and fluidics, Inertial and Resonant sensors, other sensors & actuators

Microfabrication, Integration and Packaging

Chair: Yoshio Mita, Univ of Tokyo, Japan
Co-Chair: Niels Tas, MESA+ Institute for Nanotechnology, Twente, NL

This Conference will bring together researchers, engineers and practitioners involved in the development of integration technologies and packaging for MEMS and MOEMS.

Topics of Interest

MICROFABRICATION: assembly technologies, microlithography issues for MEMS/MOEMS, micromachining, micro-molding, nano-imprint, embossing, others

INTEGRATION: flexible technologies and printed electronics, co-integration between MEMS and electronics, 3Dtechnologies

PACKAGING: MOEMS, RF and microwave, vacuum and other harsh environments, others

MATERIALS: piezoelectric, PDMS, others

CHARACTERIZATION: dimensional measurements, non-destructive evaluation, PCM & Test structures, physical measurements, reliability and failure analysis

DEVICES & COMPONENTS: RF MEMS, MOEMS, energy harvesting, bio and fluidics, Inertial and Resonant sensors, other sensors & actuators